Product Change Notification

(Notification - P1608043-DIGI)

(CST-R2-AJ095)

August 19, 2016

To: *Our Valued Digi-Key, Inc. Customer*

Overview: The purpose of this notification is to communicate product change of select Renesas Electronics America, Inc. (REA) devices.

Select SRAM products in SOP, µTSOP, & BGA packages are undergoing the following changes (see the Appendix for specific details)...

1. Final Test Site change from Renesas Semiconductor Beijing to Powertech Technology Inc.
2. Standardization of JEDEC trays and Tape & Reel specifications.

There are no changes to part numbers, electrical characteristics, or reliability & quality levels.

Affected Products: A review of our shipment records to your company indicate the attached list of products is affected by this notification.

Booking Part Number
R1LP0108ESN-5SI#B0
R1LP0408DSP-5SI#B0
R1LP5256ESP-5SI#B0
R1LV0108ESN-5SI#B0
R1LV5256ESP-5SI#B0
RMLV0408EGSP-4S2#CA0
RMLV0416EGBG-4S2#AC0

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Shipments from REA of products using the new Final Test Site and standardized JEDEC trays & Tape & Reel specifications begins. Cross shipments between the original and new products may continue for a period of time.	**Dec. 15th, 2016**

Response: No response is required. REA will consider this notification approved 30 days after its issue. If you anticipate volumes beyond your regular rate prior to the transition date, please contact your REA sales representative with a forecast of your requirements.

Please contact your REA sales representative for any questions or comments.

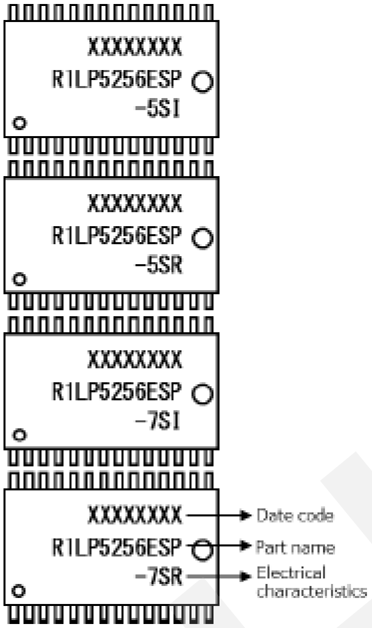
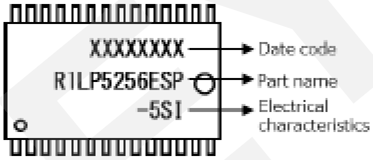
Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

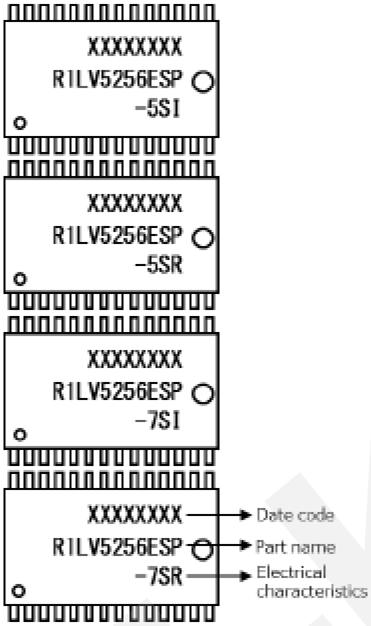
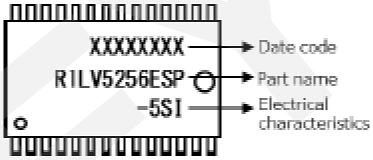
Appendix A: Change Details

(1) 28pin-SOP 256Kb(5V) Part name : R1LP5256ESP

Item		Pre Change	Post Change
Orderable part name		R1LP5256ESP-5SI/-5SR/-7SI/-7SR#B0 (Magazine packing)	R1LP5256ESP-5SI#B0 (Magazine packing)
		R1LP5256ESP-5SI/-5SR/-7SI/-7SR#S0 (Tape & Reel packing)	R1LP5256ESP-5SI#S0 (Tape & Reel packing)
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-SOP28-8.4x17.5-1.27	←
Package marking specification			
Assembly Material	Lead frame material	42Alloy	←
	Lead plating	Sn-Cu	←
	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-included)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Magazine packing	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP024PC	←
	Storage number	30pcs/magazine	←
	Number of magazines (Max.)	40 magazines	←
	Inner box size (LxWxH)	600mm x 172mm x 77mm	595mm x 170mm x 72mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Emboss type name : MTE2416H-28P2W-C	←
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
Moisture-proof performance		MSL 2	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

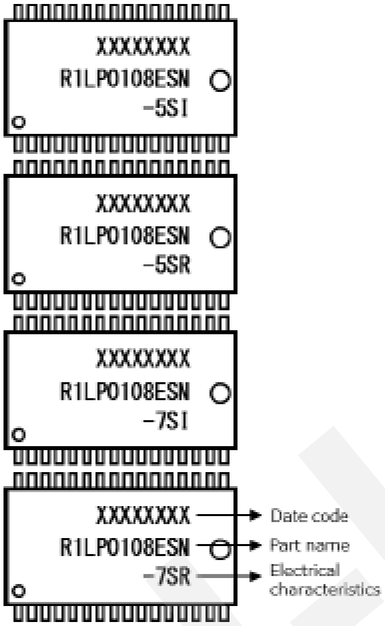
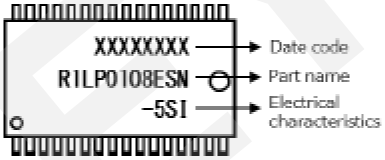
Appendix A (cont.): Change Details

(2) 28pin-SOP 256Kb(3V) Part name : R1LV5256ESP

Item		Pre Change	Post Change
Orderable part name		R1LV5256ESP-5SI/-5SR/-7SI/-7SR#B0 (Magazine packing)	R1LV5256ESP-5SI#B0 (Magazine packing)
		R1LV5256ESP-5SI/-5SR/-7SI/-7SR#S0 (Tape & Reel packing)	R1LV5256ESP-5SI#S0 (Tape & Reel packing)
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-SOP28-8.4x17.5-1.27	←
Package marking specification			
Assembly Material	Lead frame material	42Alloy	←
	Lead plating	Sn-Cu	←
	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-included)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Magazine packing	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP024PC	←
	Storage number	30pcs/magazine	←
	Number of magazines (Max.)	40 magazines	←
	Inner box size (LxWxH)	600mm x 172mm x 77mm	595mm x 170mm x 72mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Emboss type name : MTE2416H-28P2W-C	←
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
Moisture-proof performance		MSL 2	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

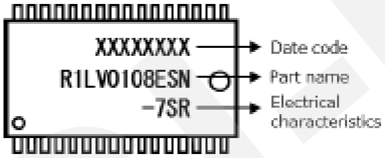
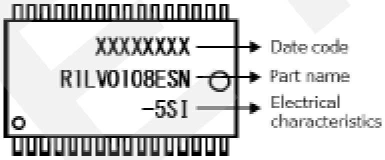
Appendix A (cont.): Change Details

(3) 32pin-SOP 1Mb(5V) Part name : R1LP0108ESN

Item		Pre Change	Post Change
Orderable part name		R1LP0108ESN-5SI/-5SR/-7SI/-7SR#B0 (Magazine packing)	R1LP0108ESN-5SI#B0 (Magazine packing)
		R1LP0108ESN-5SI/-5SR/-7SI/-7SR#S0 (Tape & Reel packing)	R1LP0108ESN-5SI#S0 (Tape & Reel packing)
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-SOP32-11.4x20.75-1.27	←
Package marking specification			
Assembly Material	Lead frame material	Cu	←
	Lead plating	Sn (pure tin)	←
	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Magazine packing	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP525PC	←
	Storage number	25pcs/magazine	←
	Number of magazines (Max.)	36 magazines	←
	Inner box size (LxWxH)	600mm x 172mm x 77mm	595mm x 170mm x 72mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Emboss type name : MTE3216H-32P2M-A	←
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

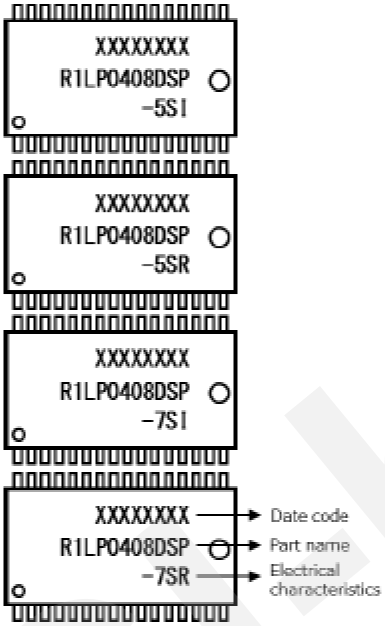
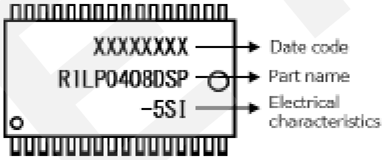
Appendix A (cont.): Change Details

(4) 32pin-SOP 1Mb(3V) Part name : R1LV0108ESN

Item		Pre Change	Post Change
Orderable part name		R1LV0108ESN-5SI/-5SR/-7SI/-7SR#B0 (Magazine packing) R1LV0108ESN-5SI/-5SR/-7SI/-7SR#S0 (Tape & Reel packing)	R1LV0108ESN-5SI#B0 (Magazine packing) R1LV0108ESN-5SI#S0 (Tape & Reel packing)
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-SOP32-11.4x20.75-1.27	←
Package marking specification		   	
Assembly Material	Lead frame material	Cu	←
	Lead plating	Sn (pure tin)	←
	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Magazine packing	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP525PC	←
	Storage number	25pcs/magazine	←
	Number of magazines (Max.)	36 magazines	←
	Inner box size (LxWxH)	600mm x 172mm x 77mm	595mm x 170mm x 72mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Emboss type name : MTE3216H-32P2M-A	←
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

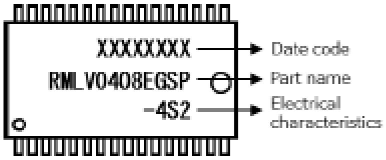
Appendix A (cont.): Change Details

(5) 32pin-SOP 4Mb(5V) Part name : R1LP0408DSP

Item		Pre Change	Post Change
Orderable part name		R1LP0408DSP-5SI/-5SR/-7SI/-7SR#B0 (Magazine packing)	R1LP0408DSP-5SI#B0 (Magazine packing)
		R1LP0408DSP-5SI/-5SR/-7SI/-7SR#S0 (Tape & Reel packing)	R1LP0408DSP-5SI#S0 (Tape & Reel packing)
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-SOP32-11.4x20.75-1.27	←
Package marking specification			
Assembly Material	Lead frame material	Cu	←
	Lead plating	Sn (pure tin)	←
	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Magazine packing	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP525PC	←
	Storage number	25pcs/magazine	←
	Number of magazines (Max.)	36 magazines	←
	Inner box size (LxWxH)	600mm x 172mm x 77mm	595mm x 170mm x 72mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Emboss type name : MTE3216H-32P2M-A	←
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

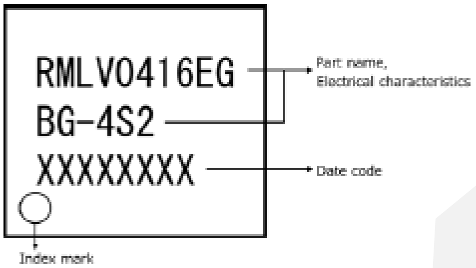
Appendix A (cont.): Change Details

(6) 32pin-SOP 4Mb(3V) Part name : RMLV0408EGSP

Item		Pre Change	Post Change
Orderable part name		RMLV0408EGSP-4S2#CA0 (Magazine packing)	←
		RMLV0408EGSP-4S2#HA0 (Tape & Reel packing)	←
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-SOP32-11.4x20.75-1.27	←
Package marking specification			No change
Assembly Material	Lead frame material	Cu	←
	Lead plating	Sn (pure tin)	←
	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Magazine packing	Packing specification	Current specification	New specification
	Magazine	Magagine code : MP525PC	←
	Storage number	25pcs/magazine	←
	Number of magazines (Max.)	36 magazines	←
	Inner box size (LxWxH)	600mm x 172mm x 77mm	595mm x 170mm x 72mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Emboss type name : MTE3216H-32P2M-A	←
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	347mm x 368mm x 54mm	362mm x 340mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

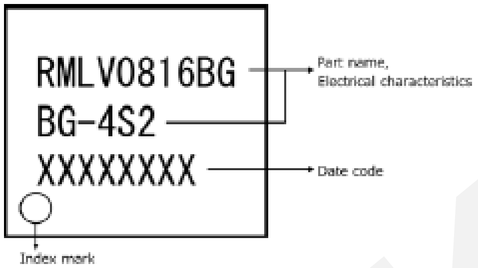
Appendix A (cont.): Change Details

(7) 48ball-FBGA 4Mb(3V) Part name : RMLV0416EGBG

Item		Pre Change	Post Change
Orderable part name		RMLV0416EGBG-4S2#AC0 (Tray packing)	←
		RMLV0416EGBG-4S2#KC0 (Tape & Reel packing)	←
Assembly line		J-Devices Kumamoto District (Japan)	←
JEITA Package Code		P-TFBGA48-7.5x8.5-0.75	←
Package marking specification			No change
Assembly Material	Substrate material	Glass epoxy	←
	Solder ball	Sn-Ag-Cu	←
	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Tray packing	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-45)	←
	Storage number	253pcs/tray	←
	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	9 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

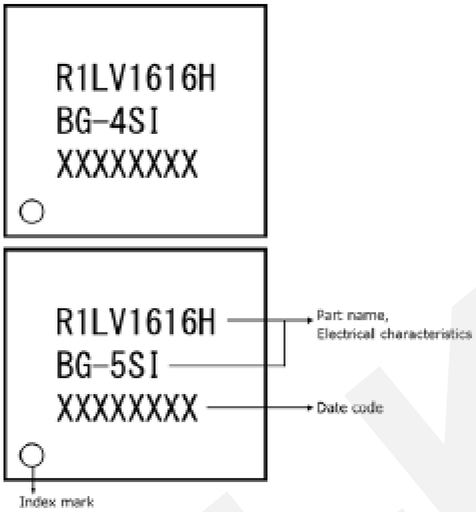
Appendix A (cont.): Change Details

(8) 48ball-FBGA 8Mb(3V) Part name : RMLV0816BGBG

Item		Pre Change	Post Change
Orderable part name		RMLV0816BGBG-4S2#AC0 (Tray packing)	←
		RMLV0816BGBG-4S2#KC0 (Tape & Reel packing)	←
Assembly line		J-Devices Kumamoto District (Japan)	←
JEITA Package Code		P-TFBGA48-7.5x8.5-0.75	←
Package marking specification			No change
Assembly Material	Substrate material	Glass epoxy	←
	Solder ball	Sn-Ag-Cu	←
	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Tray packing	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-45)	←
	Storage number	253pcs/tray	←
	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	9 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

Appendix A (cont.): Change Details

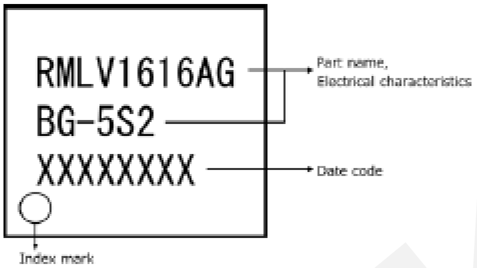
(9) 48ball-FBGA 16Mb(3V) Part name : R1LV1616HBG

Item		Pre Change	Post Change
Orderable part name		R1LV1616HBG-4SI/-5SI#B0 (Tray packing)	←
		R1LV1616HBG-4SI/-5SI#S0 (Tape & Reel packing)	←
Assembly line		J-Devices Kumamoto District (Japan)	←
JEITA Package Code		P-TFBGA48-8x9.5-0.75	←
Package marking specification		 	No change
Assembly Material	Substrate material	Glass epoxy	←
	Solder ball	Sn-Ag-Cu	←
	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-included)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Tray packing	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : PTA71C)	←
	Storage number	264pcs/tray	←
	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	9 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

- Regarding R1LV1616HBG, laser marking on the package's surface is processed at final test site.

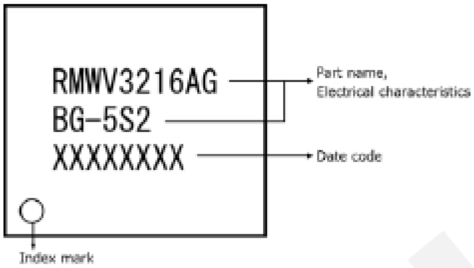
Appendix A (cont.): Change Details

(10) 48ball-FBGA 16Mb(3V) Part name : RMLV1616AGBG

Item		Pre Change	Post Change
Orderable part name		RMLV1616AGBG-5S2#AC0 (Tray packing)	←
		RMLV1616AGBG-5S2#KC0 (Tape & Reel packing)	←
Assembly line		J-Devices Kumamoto District (Japan)	←
JEITA Package Code		P-TFBGA48-7.5x8.5-0.75	←
Package marking specification			No change
Assembly Material	Substrate material	Glass epoxy	←
	Solder ball	Sn-Ag-Cu	←
	Die bonding	Epoxy paste	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Tray packing	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-45)	←
	Storage number	253pcs/tray	←
	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	9 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

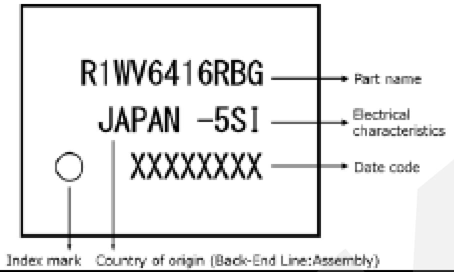
Appendix A (cont.): Change Details

(11) 48ball-FBGA 32Mb(3V) Part name : RMWV3216AGBG

Item		Pre Change	Post Change
Orderable part name		RMWV3216AGBG-5S2#AC0 (Tray packing)	←
		RMWV3216AGBG-5S2#KC0 (Tape & Reel packing)	←
Assembly line		J-Devices Kumamoto District (Japan)	←
JEITA Package Code		P-TFBGA48-7.5x8.5-0.75	←
Package marking specification			No change
Assembly Material	Substrate material	Glass epoxy	←
	Solder ball	Sn-Ag-Cu	←
	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-free)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Tray packing	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-45)	←
	Storage number	253pcs/tray	←
	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	9 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

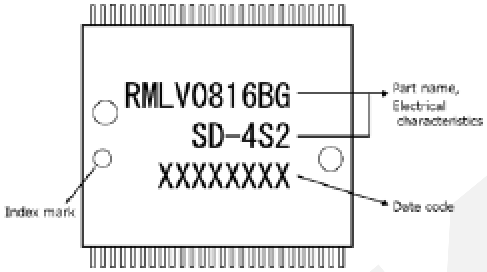
Appendix A (cont.): Change Details

(12) 48ball-FBGA 64Mb(3V) Part name : R1WV6416RBG

Item		Pre Change	Post Change
Orderable part name		R1WV6416RBG-5SI#B0 (Tray packing)	←
		R1WV6416RBG-5SI#S0 (Tape & Reel packing)	←
Assembly line		J-Devices Kumamoto District (Japan)	←
JEITA Package Code		P-TFBGA48-8.5x11-0.75	←
Package marking specification			No change
Assembly Material	Substrate material	Glass epoxy	←
	Solder ball	Sn-Ag-Cu	←
	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-included)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Tray packing	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-121)	←
	Storage number	242pcs/tray	←
	Laying direction of Ics on a tray	Direction from the bottm right position to the up side (when the position of chamfer in tray's corner is bottom left.)	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)
	Number of trays (Max.)	8 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 3	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

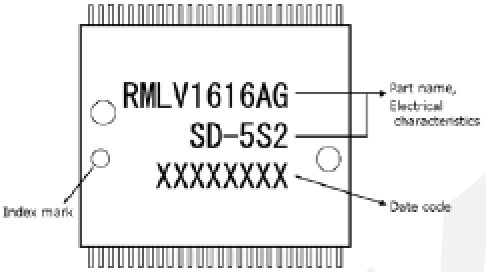
Appendix A (cont.): Change Details

(13) 52pin-μTSOP 8Mb(3V) Part name : RMLV0816BGSD

Item		Pre Change	Post Change
Orderable part name		RMLV0816BGSD-4S2#AC0 (Tray packing)	←
		RMLV0816BGSD-4S2#HC0 (Tape & Reel packing)	←
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-TSOP(2)52-8.89x10.79-0.40	←
Package marking specification			No change
Assembly Material	Lead frame material	42Alloy	←
	Lead plating	Sn-Cu	←
	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-included)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Tray packing	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-24)	←
	Storage number	230pcs/tray	←
	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	8 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 2	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

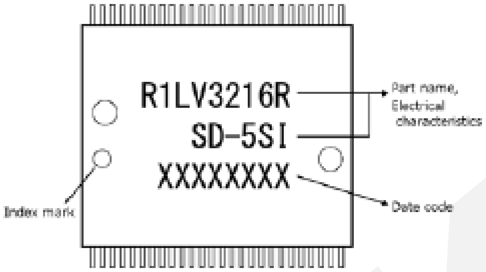
Appendix A (cont.): Change Details

(14) 52pin-μTSOP 16Mb(3V) Part name : RMLV1616AGSD

Item		Pre Change	Post Change
Orderable part name		RMLV1616AGSD-5S2#AC0 (Tray packing)	←
		RMLV1616AGSD-5S2#HC0 (Tape & Reel packing)	←
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-TSOP(2)52-8.89x10.79-0.40	←
Package marking specification			No change
Assembly Material	Lead frame material	42Alloy	←
	Lead plating	Sn-Cu	←
	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-included)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Tray packing	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-24)	←
	Storage number	230pcs/tray	←
	Laying direction of Ics on a tray	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)	←
	Number of trays (Max.)	8 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 2	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

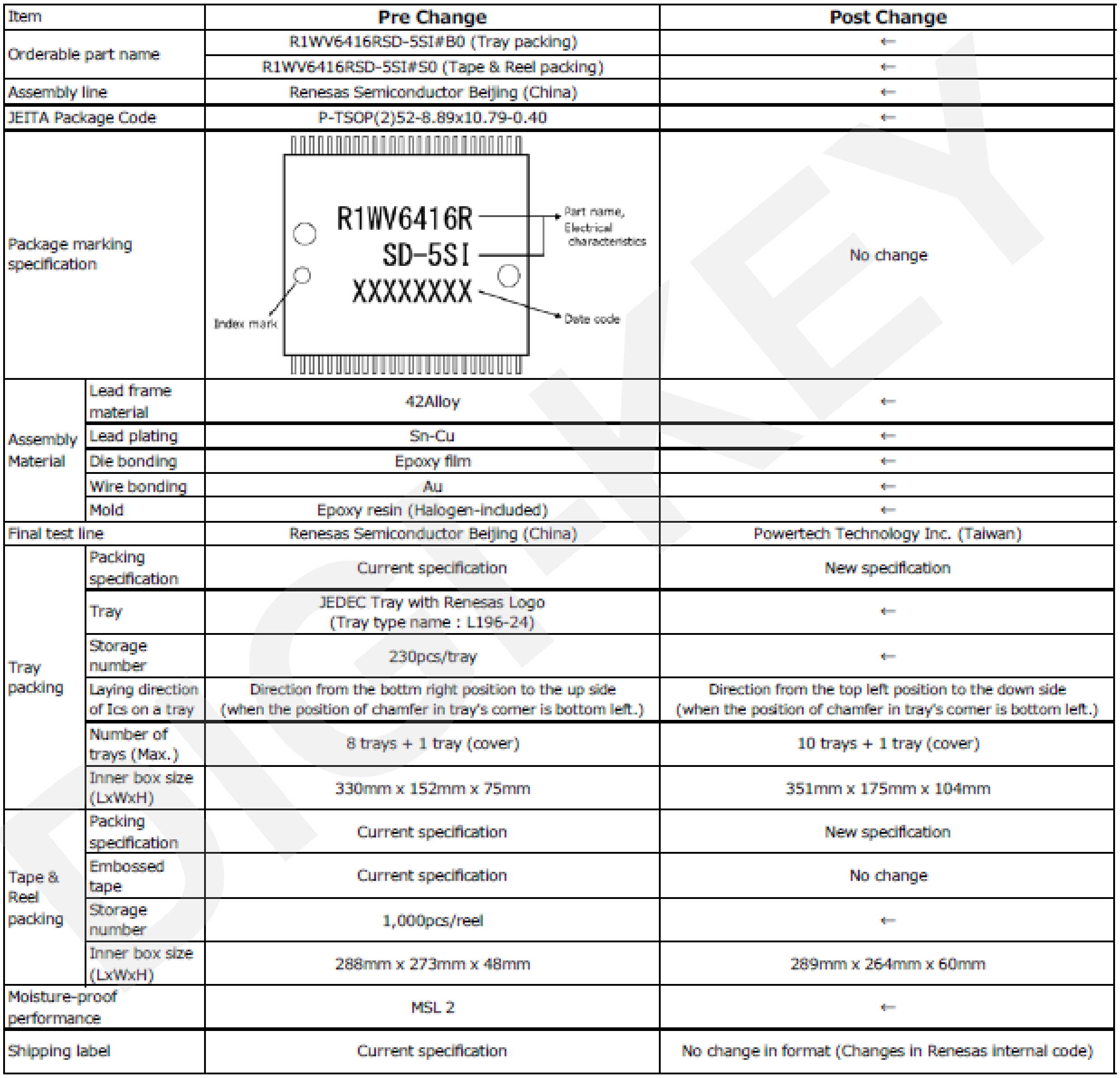
Appendix A (cont.): Change Details

(15) 52pin-µTSOP 32Mb(3V) Part name : R1LV3216RSD

Item		Pre Change	Post Change
Orderable part name		R1LV3216RSD-5SI#B0 (Tray packing)	←
		R1LV3216RSD-5SI#S0 (Tape & Reel packing)	←
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-TSOP(2)52-8.89x10.79-0.40	←
Package marking specification			No change
Assembly Material	Lead frame material	42Alloy	←
	Lead plating	Sn-Cu	←
	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-included)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Tray packing	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-24)	←
	Storage number	230pcs/tray	←
	Laying direction of Ics on a tray	Direction from the bottm right position to the up side (when the position of chamfer in tray's corner is bottom left.)	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)
	Number of trays (Max.)	8 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 2	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

Appendix A (cont.): Change Details

(16) 52pin-μTSOP 64Mb(3V) Part name : R1WV6416RSD



Item		Pre Change	Post Change
Orderable part name		R1WV6416RSD-5SI#B0 (Tray packing)	←
		R1WV6416RSD-5SI#S0 (Tape & Reel packing)	←
Assembly line		Renesas Semiconductor Beijing (China)	←
JEITA Package Code		P-TSOP(2)52-8.89x10.79-0.40	←
Package marking specification		R1WV6416R SD-5SI XXXXXXXX Part name, Electrical characteristics Date code Index mark	No change
Assembly Material	Lead frame material	42Alloy	←
	Lead plating	Sn-Cu	←
	Die bonding	Epoxy film	←
	Wire bonding	Au	←
	Mold	Epoxy resin (Halogen-included)	←
Final test line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)
Tray packing	Packing specification	Current specification	New specification
	Tray	JEDEC Tray with Renesas Logo (Tray type name : L196-24)	←
	Storage number	230pcs/tray	←
	Laying direction of Ics on a tray	Direction from the bottm right position to the up side (when the position of chamfer in tray's corner is bottom left.)	Direction from the top left position to the down side (when the position of chamfer in tray's corner is bottom left.)
	Number of trays (Max.)	8 trays + 1 tray (cover)	10 trays + 1 tray (cover)
	Inner box size (LxWxH)	330mm x 152mm x 75mm	351mm x 175mm x 104mm
Tape & Reel packing	Packing specification	Current specification	New specification
	Embossed tape	Current specification	No change
	Storage number	1,000pcs/reel	←
	Inner box size (LxWxH)	288mm x 273mm x 48mm	289mm x 264mm x 60mm
Moisture-proof performance		MSL 2	←
Shipping label		Current specification	No change in format (Changes in Renesas internal code)

Appendix B: Packaging Specification Change

- Regarding R1LV3216RSD-5SI, R1WV6416RSD-5SI and R1WV6416RBG-5SI, laying direction of ICs on a tray is to be changed (see below).
- No change in other products, because the direction is already same as the "Post Change" as shown below.

	Pre Change	Post Change
Laying direction of ICs on a tray		
Orderable part name	R1LV3216RSD-5SI#B0 R1WV6416RSD-5SI#B0 R1WV6416RBG-5SI#B0	R1LV3216RSD-5SI#B0 R1WV6416RSD-5SI#B0 R1WV6416RBG-5SI#B0